

74ALVC32

Quad 2-input OR gate

Rev. 3 — 20 January 2014

Product data sheet

1. General description

The 74ALVC32 is a quad 2-input OR gate.

Schmitt trigger action on all inputs makes the device tolerant of slow rise and fall times.

2. Features and benefits

- Wide supply voltage range from 1.65 V to 3.6 V
- 3.6 V tolerant inputs/outputs
- CMOS low power consumption
- Direct interface with TTL levels (2.7 V to 3.6 V)
- Power-down mode
- Latch-up performance exceeds 250 mA
- Complies with JEDEC standards:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V

3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74ALVC32D	-40 °C to +85 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74ALVC32PW	-40 °C to +85 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74ALVC32BQ	-40 °C to +85 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1



4. Functional diagram

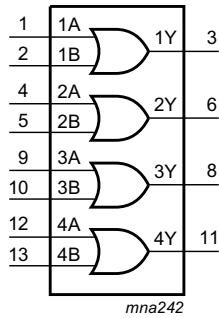


Fig 1. Logic symbol

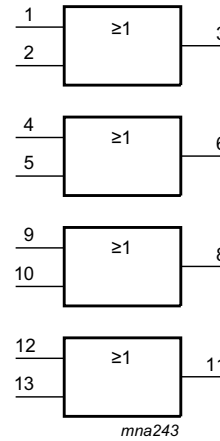


Fig 2. IEC logic symbol

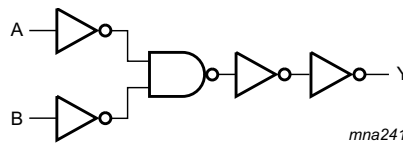


Fig 3. Logic diagram (one gate)

5. Pinning information

5.1 Pinning

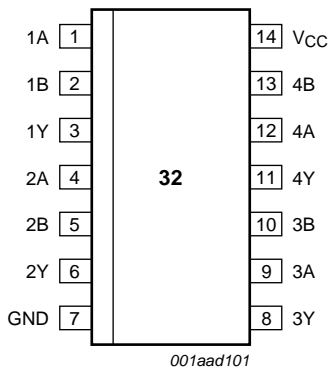
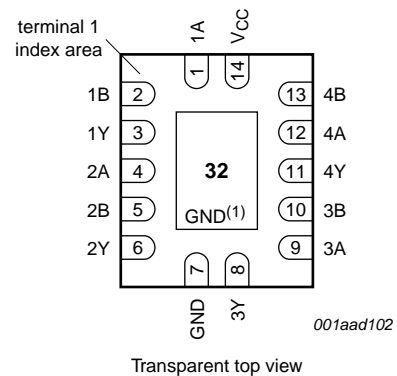


Fig 4. Pin configuration SO14 and TSSOP14



- (1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration DHVQFN14

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
nA	1, 4, 9, 12	data input
nB	2, 5, 10, 13	data input
nY	3, 6, 8, 11	data output
V _{CC}	14	supply voltage
GND	7	ground (0 V)

6. Functional description

Table 3. Function table^[1]

Input nA	Input nB	Output nY
L	L	L
L	H	H
H	L	H
H	H	H

- [1] H = HIGH voltage level
L = LOW voltage level

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage		-0.5	+4.6	V
I _{OK}	output clamping current	V _O > V _{CC} or V _O < 0 V	-	±50	mA
V _O	output voltage	output HIGH or LOW state	^[1] ^[2] -0.5	V _{CC} + 0.5	V
		output 3-state	-0.5	+4.6	V
		power-down mode, V _{CC} = 0 V	^[2] -0.5	+4.6	V
I _O	output current	V _O = 0 V to V _{CC}	-	±50	mA
I _{CC}	supply current		-	100	mA
I _{GND}	ground current		-100	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +85 °C	^[3] -	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 [2] When V_{CC} = 0 V (power-down mode), the output voltage can be 3.6 V in normal operation.
 [3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.
 For TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.
 For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		1.65	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	output HIGH or LOW state	0	V_{CC}	V
		output 3-state	0	3.6	V
		power-down mode; $V_{CC} = 0$ V	0	3.6	V
T_{amb}	ambient temperature	in free air	-40	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	0	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$T_{amb} = -40$ °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	-	-	V
		$V_{CC} = 2.7$ V to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	-	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = -100$ μ A; $V_{CC} = 1.65$ V to 3.6 V	$V_{CC} - 0.2$	-	-	V
		$I_O = -6$ mA; $V_{CC} = 1.65$ V	1.25	1.51	-	V
		$I_O = -12$ mA; $V_{CC} = 2.3$ V	1.8	2.10	-	V
		$I_O = -18$ mA; $V_{CC} = 2.3$ V	1.7	2.01	-	V
		$I_O = -12$ mA; $V_{CC} = 2.7$ V	2.2	2.53	-	V
		$I_O = -18$ mA; $V_{CC} = 3.0$ V	2.4	2.76	-	V
		$I_O = -24$ mA; $V_{CC} = 3.0$ V	2.2	2.68	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = 100$ μ A; $V_{CC} = 1.65$ V to 3.6 V	-	-	0.2	V
		$I_O = 6$ mA; $V_{CC} = 1.65$ V	-	0.11	0.3	V
		$I_O = 12$ mA; $V_{CC} = 2.3$ V	-	0.17	0.4	V
		$I_O = 18$ mA; $V_{CC} = 2.3$ V	-	0.25	0.6	V
		$I_O = 12$ mA; $V_{CC} = 2.7$ V	-	0.16	0.4	V
		$I_O = 18$ mA; $V_{CC} = 3.0$ V	-	0.23	0.4	V
		$I_O = 24$ mA; $V_{CC} = 3.0$ V	-	0.30	0.55	V
I_I	input leakage current	$V_{CC} = 3.6$ V; $V_I = 3.6$ V or GND	-	± 0.1	± 5	μ A
I_{OFF}	power-off leakage current	$V_{CC} = 0$ V; V_I or $V_O = 0$ V to 3.6 V	-	± 0.1	± 10	μ A

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T _{amb} = -40 °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A	-	0.2	10	μA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 3.0 V to 3.6 V; V _I = V _{CC} - 0.6 V; I _O = 0 A	-	5	750	μA
C _I	input capacitance		-	3.5	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	T _{amb} = -40 °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
t _{pd}	propagation delay	CP to Qn; see Figure 6 ^[2]				
		V _{CC} = 1.65 V to 1.95 V	1.0	2.8	4.7	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.0	3.1	ns
		V _{CC} = 2.7 V	1.0	2.2	2.9	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.0	2.8	ns
C _{PD}	power dissipation capacitance	per gate; V _I = GND to V _{CC} ; V _{CC} = 3.3 V ^[3]	-	25	-	pF

[1] Typical values are measured at T_{amb} = 25 °C

[2] t_{pd} is the same as t_{PHL} and t_{PLH}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz; f_o = output frequency in MHz

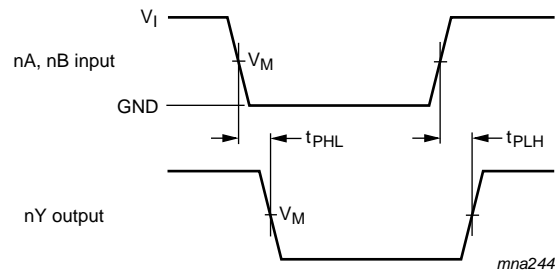
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

Σ(C_L × V_{CC}² × f_o) = sum of the outputs

11. Waveforms

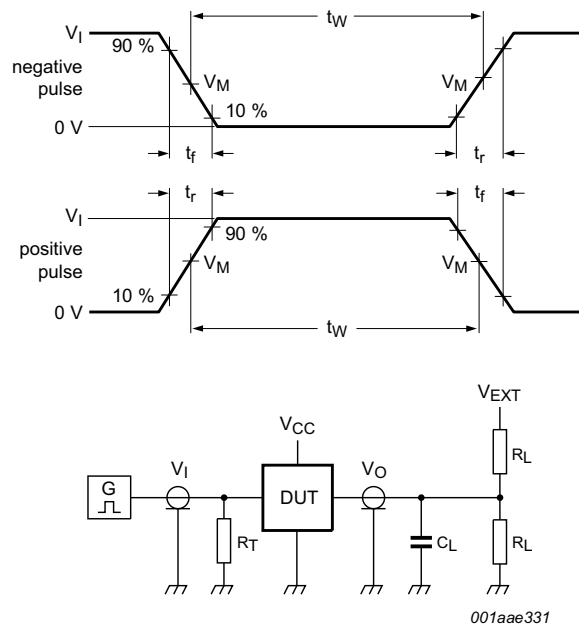


Measurement points are given in [Table 8](#).

Fig 6. Inputs nA, nB to output nY propagation delay times

Table 8. Measurement points

Supply voltage V_{CC}	Input V_I	V_M
1.65 V to 1.95 V	V_{CC}	$0.5V_{CC}$
2.3 V to 2.7 V	V_{CC}	$0.5V_{CC}$
2.7 V	2.7 V	1.5 V
3.0 V to 3.6 V	2.7 V	1.5 V



Test data is given in [Table 9](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 7. Test circuitry for measuring switching times

Table 9. Test data

Supply voltage V_{CC}	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.65 V to 1.95 V	V_{CC}	≤ 2.0 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	V_{CC}	≤ 2.0 ns	30 pF	500 Ω	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	6 V	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	6 V	GND

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

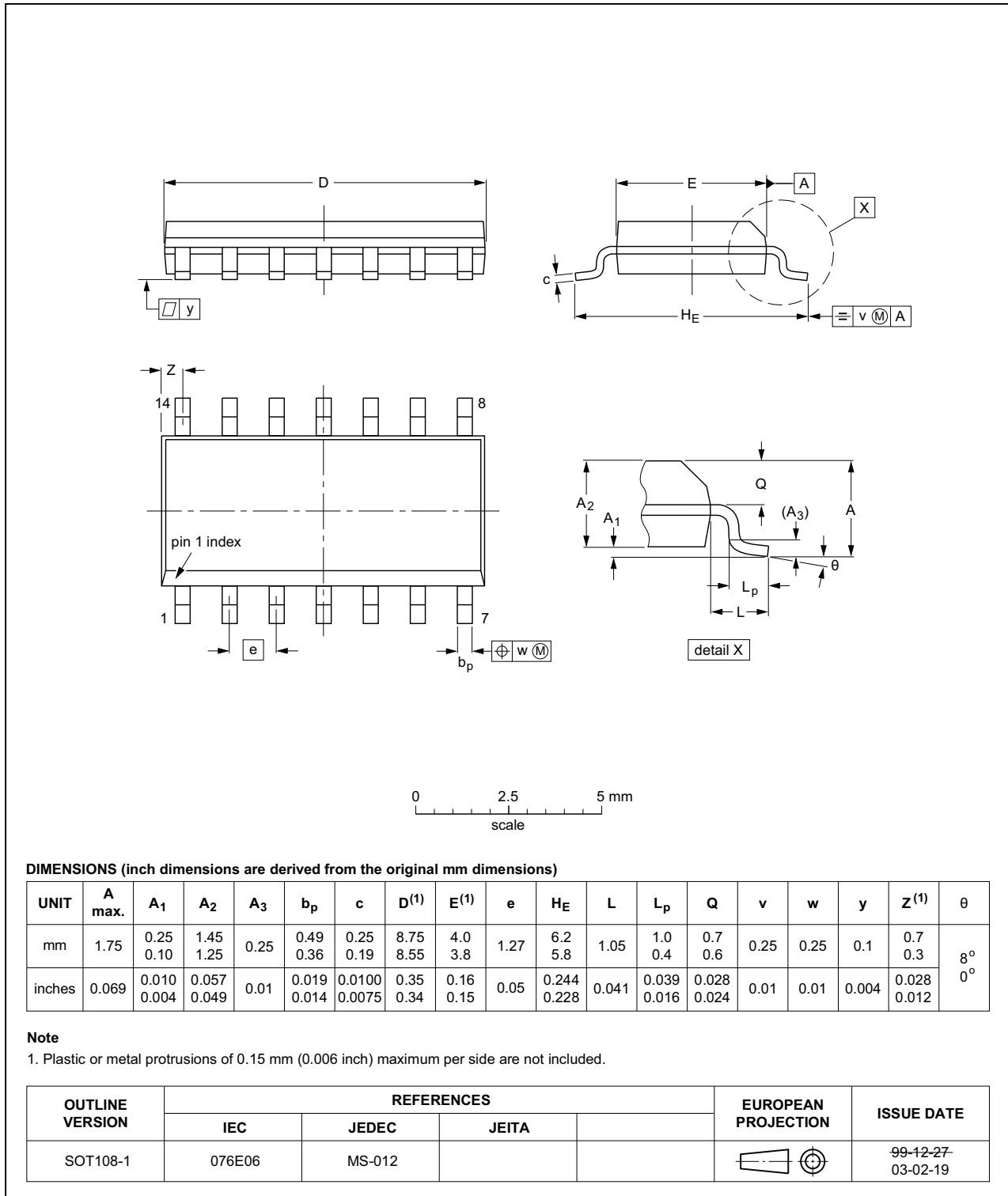


Fig 8. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



Fig 9. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

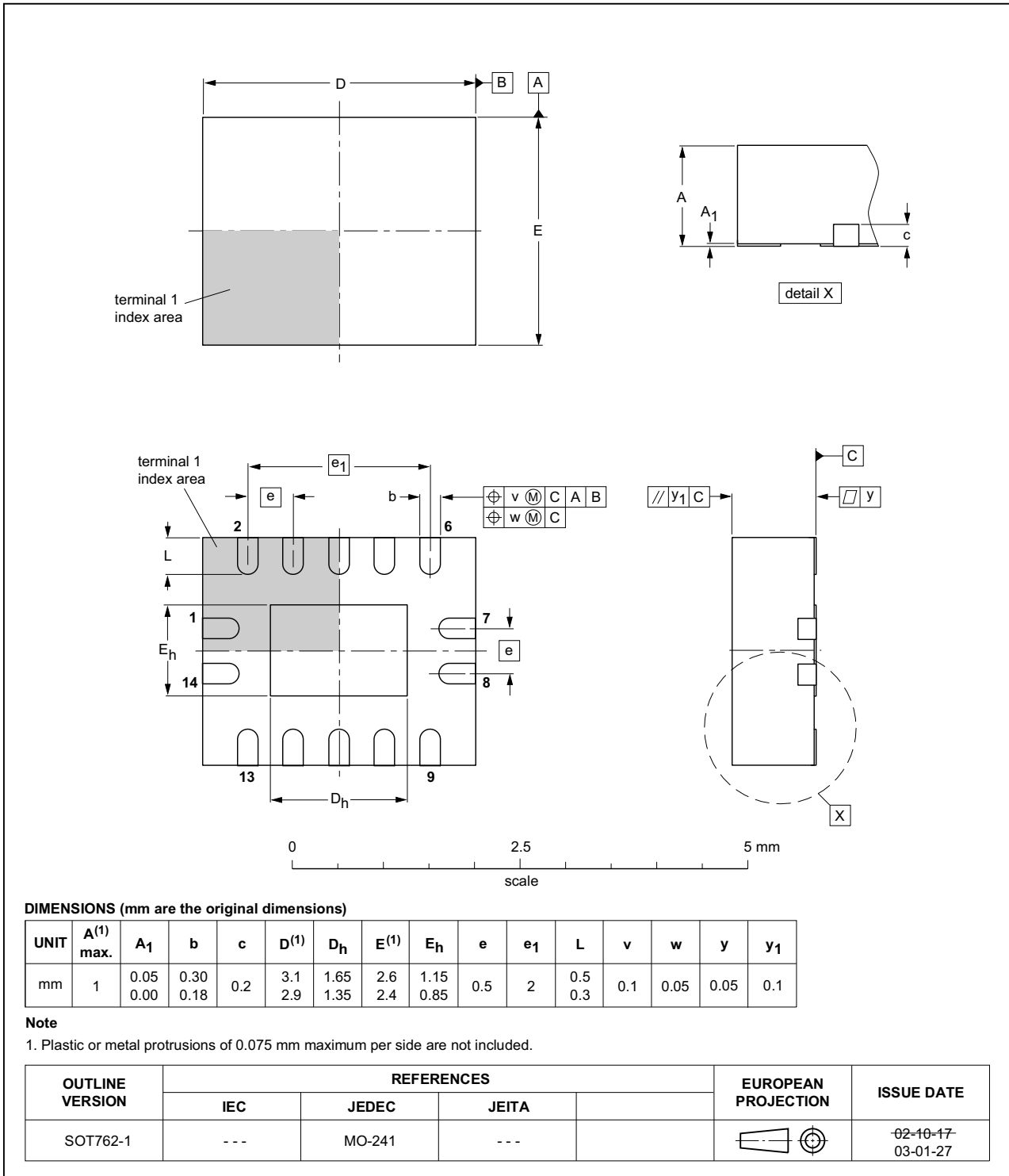


Fig 10. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVC32 v.3	20140120	Product data sheet	-	74ALVC32 v.2
		<ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.Legal texts have been adapted to the new company name where appropriate.		
74ALVC32 v.2	20071210	Product data sheet	-	74ALVC32 v.1
74ALVC32 v.1	20021115	Product specification	-	-

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Document status ^{[1][2]}	Product status ^[3]	Definition
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